

Appl. No. 10/727,740
Reply to Office action of 01/05/2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-17 (Canceled).

18. (Currently amended) A fabrication method, comprising the steps of:
varying the history of wafers within a lot by transporting individual ones wafers thereof
within a processing tool with multiple processing chambers,
among said chambers and wafer cassette and/or staging locations
in various different sequences.
19. (Original) The method of Claim 18, further comprising the contemporaneous step of
recording process sequence data for said wafers.
20. (Original) The method of Claim 18, further comprising the subsequent step of
correlating fault and/or parametric data with process sequence data resulting from
said varying step.
21. (Original) The method of Claim 18, further comprising the subsequent step of
correlating fault and/or parametric data with process sequence data resulting from
said varying step, and controlling process parameters accordingly.
- 22-26. (Cancelled).
27. (new) The method of claim 18, wherein said chambers are randomly selected during
said varying step.